

Available on commercial versions	<u>Qualified Levels</u> : JAN, JANTX, JANTXV and JANS						
	DESCRIPTION						
This family of 2N2904AL JANS level for high-reliab package. Microsemi also power ratings with variou mount packages.							
Important: For the latest inform	nation, visit our website <u>http://www.micros</u> FEATURES	emi.com.					
· ·	904 through 2N2905 series.				TO-5 Package		
	and JANS qualifications are availabl	e per MIL-PR	F-19500/290.		_		
	of or all available options.)						
RoHS compliant version	ns available (commercial grade only)				Also available in:		
	PDF Sunna						
	APPLICATIONS / BENER	ITS			(long-leaded)		
Military and other high-	stors for high speed switching applica reliability applications. MAXIMUM RATINGS rs / Test Conditions		Value	Unit			
Collector-Emitter Voltage		V <sub>CEO</sub>	60	V			
Collector-Base Voltage		V <sub>CBO</sub>	60	V			
Emitter-Base Voltage		V <sub>EBO</sub>	5.0	V			
Thermal Resistance Junct	ion-to-Ambient	R <sub>eja</sub>	195	°C/W	MSC – Lawrence		
Thermal Resistance Junct		R <sub>ejc</sub>	50	°C/W	6 Lake Street, Lawrence, MA 01841		
Collector Current		IC	600	mA	Tel: 1-800-446-1158 or		
Total Power Dissipation	@ $T_A = +25 \degree C^{(1)}$ @ $T_C = +25 \degree C^{(2)}$	P <sub>T</sub>	0.8	W	(978) 620-2600 Fax: (978) 689-0803		
Operating & Storage Junc	-	$T_J$ and $T_{stq}$	-65 to +200	°C	MSC – Ireland		
Notes: 1. For derating, se		9			Gort Road Business Park, Ennis, Co. Clare, Ireland Tel: +353 (0) 65 6840044 Fax: +353 (0) 65 6822298		

# Website:

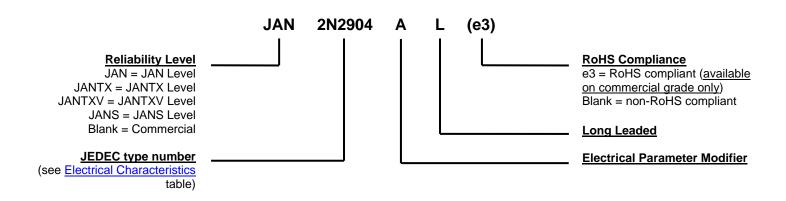
www.microsemi.com



## **MECHANICAL and PACKAGING**

- CASE: Hermetically sealed, kovar base, nickel cap.
- TERMINALS: Tin/lead plate or RoHS compliant matte/tin (commercial grade only) over nickel.
- MARKING: Part number, date code, manufacturer's ID.
- POLARITY: PNP (see package outline).
- WEIGHT: Approximately 1.14 grams.
- See <u>Package Dimensions</u> on last page.

## PART NOMENCLATURE



	SYMBOLS & DEFINITIONS				
Symbol	Definition				
C <sub>obo</sub>	Common-base open-circuit output capacitance.				
I <sub>CEO</sub>	Collector cutoff current, base open.				
I <sub>CEX</sub>	Collector cutoff current, circuit between base and emitter.				
I <sub>EBO</sub>	Emitter cutoff current, collector open.				
h <sub>FE</sub>	Common-emitter static forward current transfer ratio.				
V <sub>CEO</sub>	Collector-emitter voltage, base open.				
V <sub>CBO</sub>	Collector-emitter voltage, emitter open.				
V <sub>EBO</sub>	Emitter-base voltage, collector open.				



Parameters / Te	st Conditions	Symbol	Min.	Max.	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown C $I_{\rm C} = 10 \text{ mA}$	urrent	V <sub>(BR)CEO</sub>	60		V
Collector-Emitter Cutoff Voltage $V_{CE} = 60 \text{ V}$	9	I <sub>CES</sub>		1.0	μA
Collector-Base Cutoff Current					
$V_{CB} = 60 \text{ V}$ All	Types	I <sub>CBO1</sub>		10	μA
V <sub>CB</sub> = 50 V 2N	12904AL, 2N2905AL	I <sub>CBO2</sub>		10	nA
$V_{CB} = 50 \text{ V} @ T_A = +150 \text{ °C} 2N$	12904AL, 2N2905AL	I <sub>CBO3</sub>		10	μA
Collector-Base Cutoff Current					
$V_{CB} = 50 V$		I <sub>CBO</sub>		10	nA
V <sub>CB</sub> = 60 V				10	μA
Emitter-Base Cutoff Current					
V <sub>EB</sub> = 3.5 V		I <sub>EBO</sub>		50	nA
V <sub>EB</sub> = 5.0 V				10	μA
ON CHARACTERISTICS (1)					
Forward-Current Transfer Ratio	)				
$I_{C} = 0.1 \text{ mA}, V_{CE} = 10 \text{ V}$	2N2904AL 2N2905AL		40 75		
$I_{C}$ = 1.0 mA, $V_{CE}$ = 10 V	2N2904AL 2N2905AL		40 100	175 450	
$I_{C}$ = 10 mA, $V_{CE}$ = 10 V	2N2904AL 2N2905AL	h <sub>FE</sub>	40 100		
$I_{C}$ = 150 mA, $V_{CE}$ = 10 V	2N2904AL 2N2905AL		40 100	120 300	
$I_{C} = 500 \text{ mA}, V_{CE} = 10 \text{ V}$	2N2904AL 2N2905AL		40 50		
Collector-Emitter Saturation Vo	Itage				
$I_{\rm C} = 150$ mA, $I_{\rm B} = 15$ mA		V <sub>CE(sat)</sub>		0.4	V
$I_{\rm C} = 500$ mA, $I_{\rm B} = 50$ mA		()		1.6	
Base-Emitter Saturation Voltag	е				
$I_{\rm C} = 150$ mA, $I_{\rm B} = 15$ mA		V <sub>BE(sat)</sub>		1.3	V
$I = 500 \text{ m}  I = 50 \text{ m}  \Lambda$		1		26	1

ELECTRICAL	. CHARACTERISTICS @ 1	[ <sub>^</sub> = +25 °C.	unless otherwise noted
		A - L = 0	

(1) Pulse Test: Pulse Width = 300  $\mu$ s, duty cycle  $\leq$  2.0%.

 $I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 50 \text{ mA}$ 

2.6



# **ELECTRICAL CHARACTERISTICS** @ $T_A = +25$ °C, unless otherwise noted (continued)

#### **DYNAMIC CHARACTERISTICS**

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Small-Signal Short-Circuit Forward-Current				
Transfer Ratio				
I <sub>C</sub> = 1.0 mA, V <sub>CE</sub> = 10 V, f = 1.0 kHz	h <sub>fe</sub>		100	
Small-Signal Short-Circuit Forward-Current				
Transfer Ratio	h <sub>fe</sub>		2.0	
$I_{C} = 50 \text{ mA}, V_{CE} = 20 \text{ V}, \text{ f} = 100 \text{ MHz}$				
Output Capacitance	6			۶L
$V_{CB}$ = 10 V, $I_{E}$ = 0, 100 kHz $\leq f \leq$ 1.0MHz	C <sub>obo</sub>		8.0	pF
lutput Capacitance				~ <b>Г</b>
$V_{EB}$ = 2.0 V, $I_C$ = 0, 100 kHz $\leq f \leq$ 1.0MHz	C <sub>ibo</sub>		30	pF

## SWITCHING CHARACTERISTICS

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Turn-On Time	ton		45	ns
Turn-Off Time	<sup>t</sup> off		300	ns



GRAPHS

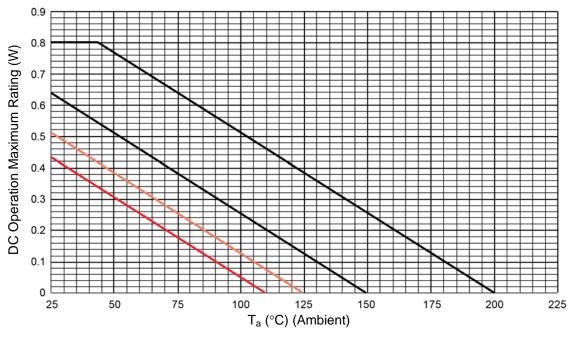
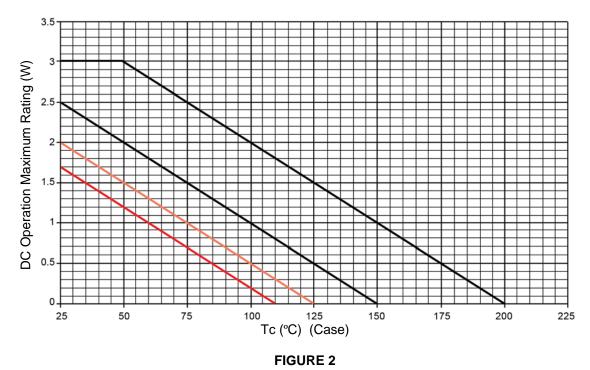


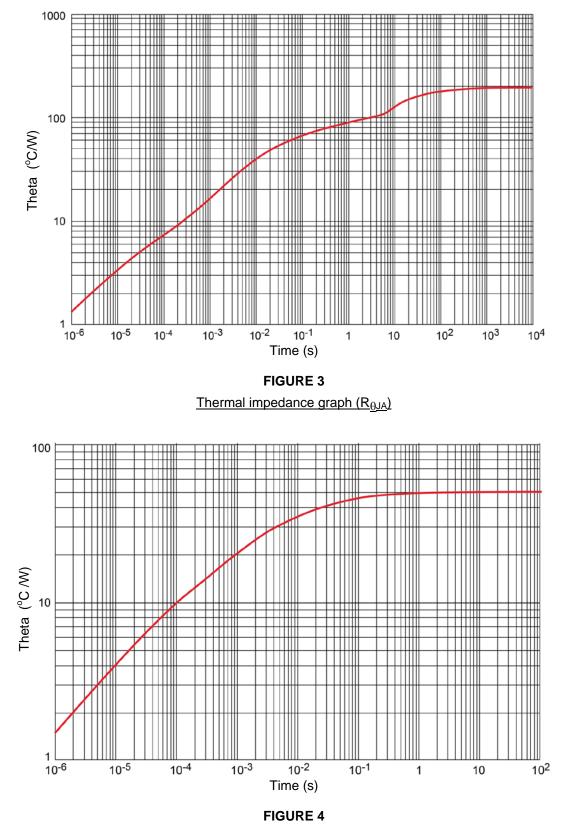
FIGURE 1 Derating (R<sub>0JA</sub>) PCB



Derating (R<sub>0JA</sub>) PCB



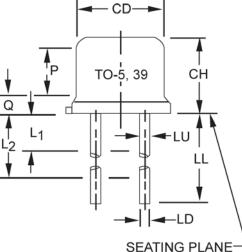
**GRAPHS** (continued)



<u>Thermal impedance graph (R<sub>0JA</sub>)</u>

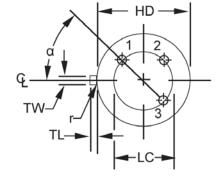


## PACKAGE DIMENSIONS



⊢LD \	Lź
	Р
NG PLANE	Q

	Dimensions				
Symbol	In	ch	Millim	Millimeters	
	Min	Max	Min	Max	
CD	0.305	0.335	7.75	8.51	
СН	0.240	0.260	6.10	6.60	
HD	0.335	0.370	8.51	9.40	
LC	0.20	0 TP	5.08	5 TP	6
LD	0.016	0.021	0.41	0.53	7, 8
LL	0.500	0.750	12.70	19.05	7, 8, 12
LU	0.016	0.019	0.41	0.48	7, 8
L1		0.050		1.27	7, 8
L2	0.250		6.35		7, 8
Р	0.100		2.54		
Q		0.050		1.27	5
TL	0.029	0.045	0.74	1.14	4
тw	0.028	0.034	0.71	0.86	3
r		0.010		0.25	10
α	45	° TP	45° TP		6



#### NOTES:

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Beyond r (radius) maximum, TW shall be held for a minimum length of .011 (0.28 mm).
- 4. Dimension TL measured from maximum HD.
- 5. Body contour optional within zone defined by HD, CD, and Q.
- 6. Leads at gauge plane .054 +.001 -.000 inch (1.37 +0.03 -0.00 mm) below seating plane shall be within .007 inch (0.18 mm) radius of true position (TP) at maximum material condition (MMC) relative to tab at MMC.
- 7. Dimension LU applies between L1 and L2. Dimension LD applies between L2 and LL minimum. Diameter is uncontrolled in L1 and beyond LL minimum.
- 8. All three leads.
- 9. The collector shall be internally connected to the case.
- 10. Dimension r (radius) applies to both inside corners of tab.
- 11. In accordance with ASME Y14.5M, diameters are equivalent to  $\Phi x$  symbology.
- 12. For "L" suffix devices, dimension LL is 1.50 (38.10 mm) minimum, 1.75 (44.45 mm) maximum.
- 13. Lead 1 =emitter, lead 2 =base, lead 3 =collector.